

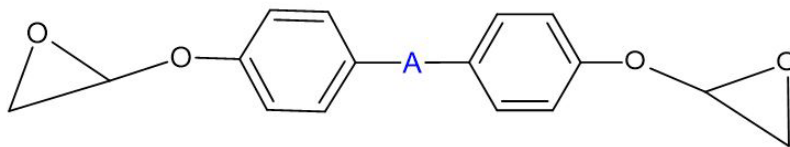
技術特色

- 具導熱與低損失樹脂結構設計
- 具低極性基團改善傳統環氧樹脂高損失特性
- 導熱樹脂具溶劑可溶性

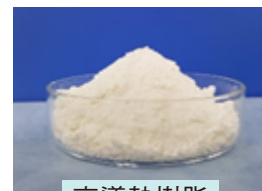
High K and Low Loss Build up film

Item		MCL(A)	MCL(B)	A公司
Dielectric property	Dk 10GHz	3.2	3.1	3.3@5.8GHz
	Df 10GHz	0.005	~0.004	0.0044@5.8GHz
Glass temperature (Tg · °C)		170	180	153
xy-CTE(ppm/°C)		20	18	20
Peel strength (kgf/cm)		0.4~0.5	0.4~0.5	0.45~0.5
Thermal conductivity (W/mK)		-	0.62	-
UL94 (VTM-0)		V0	V0	V0

Low Loss Resin



A : aliphatic 、 aromatic group

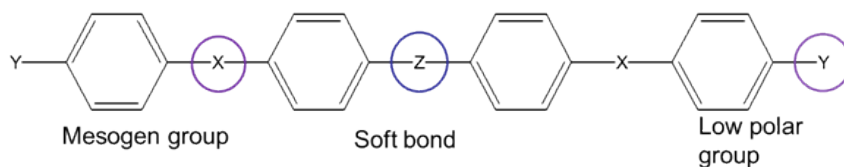


高導熱樹脂

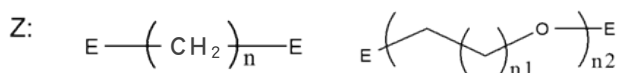


卷狀增層材料 (ABF like)

High K & Low Loss Resin

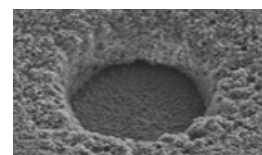


X : Ester group 、 enylene group 、 imine group 、 ketone group



Y: Allyl 、 Vinyl 、 Acrylate

SAP process(MCL(A))



Laser Via formation(40µm)



Electless copper plating (40µm)